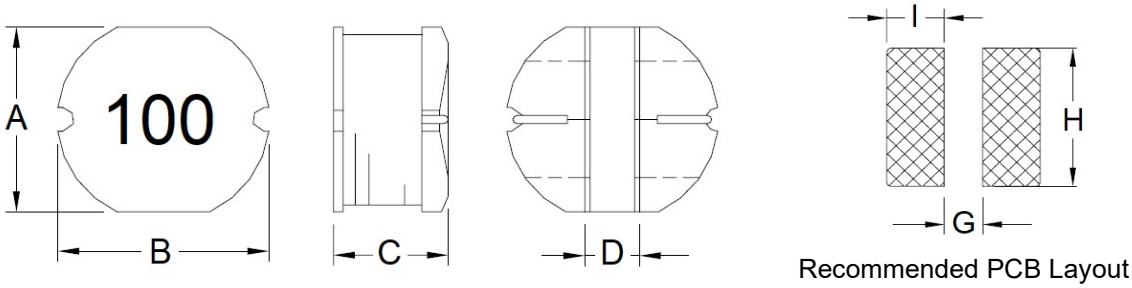
1. Part No. Expression

P D C 1 0 0 4 1 0 0 M Z F

(a) (b) (c) (d) (e) (f)

(a)	Series Code	(d)	Tolerance Code
(b)	Dimension Code	(e)	Special Code
(c)	Inductance Code	(f)	Packaging Code

2. Configuration & Dimensions (Unit: mm)



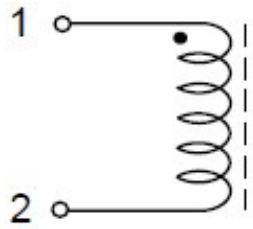
Recommended PCB Layout

Note: 1. The above PCB layout reference only.

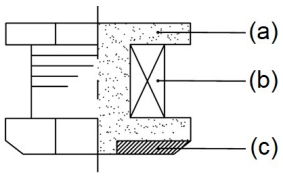
2. Marking: Inductance Code

A	B	C	D	G	H	I
9.00±0.30	10.00±0.30	4.00±0.50	3.00±0.30	2.50 Ref	9.50 Ref	3.75 Ref

3. Schematic



4. Material List



(a) Core
(b) Wire
(c) Electrode

5. General Specifications

(a) Operating Temp.: -40°C to +125°C (including self-temperature rise)
(b) Storage Temp.: -40°C to +125°C (on board)
(c) All test data referenced to 25°C ambient.
(d) Heat Rated Current (Irms) will cause the coil temperature rise ΔT of 40°C Max.
(e) Saturation Current (Isat) will cause inductance L0 to drop approximately 10%.
(f) Rated Current: The lower value of Isat and Irms.
(g) Storage Condition (Component in its packaging)
  i) Temperature: 25°C±5°C
  ii) Humidity: 35% ~ 70% RH

6. Electrical Characteristics

Part Number	Inductance (uH) @0A	Test Frequency	DCR (Ω) Max	IDC (mA)	Marking
PDC1004100MZF	10	1V/2.52MHz	0.053	2.38	100
PDC1004120MZF	12	1V/2.52MHz	0.061	2.13	120
PDC1004150MZF	15	1V/2.52MHz	0.070	1.87	150
PDC1004180MZF	18	1V/2.52MHz	0.081	1.73	180
PDC1004220MZF	22	1V/2.52MHz	0.088	1.60	220
PDC1004270MZF	27	1V/2.52MHz	0.100	1.44	270
PDC1004330MZF	33	1V/2.52MHz	0.120	1.26	330
PDC1004390MZF	39	1V/2.52MHz	0.151	1.20	390
PDC1004470KZF	47	1V/2.52MHz	0.170	1.10	470
PDC1004560KZF	56	1V/2.52MHz	0.199	1.01	560
PDC1004680KZF	68	1V/2.52MHz	0.223	0.91	680
PDC1004820KZF	82	1V/2.52MHz	0.252	0.85	820
PDC1004101KZF	100	1V/1KHz	0.344	0.74	101
PDC1004121KZF	120	1V/1KHz	0.396	0.69	121
PDC1004151KZF	150	1V/1KHz	0.544	0.61	151
PDC1004181KZF	180	1V/1KHz	0.621	0.56	181
PDC1004221KZF	220	1V/1KHz	0.721	0.53	221
PDC1004271KZF	270	1V/1KHz	0.949	0.45	271
PDC1004331KZF	330	1V/1KHz	1.100	0.42	331
PDC1004391KZF	390	1V/1KHz	1.245	0.38	391
PDC1004471KZF	470	1V/1KHz	1.526	0.35	471
PDC1004561KZF	560	1V/1KHz	1.904	0.32	561

Note:

Tolerance Code: K= ±10%, M= ±20%

7. Soldering Specification

Mildly activated rosin fluxes are preferred. Our terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

7-1. IR Soldering Reflow

Recommended temperature profiles for lead free re-flow soldering in Figure 1, Table 1.1 & 1.2 (J-STD-020F).

7-2. Iron Reflow

Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended (Figure 2).

Note:

(a) Preheat circuit and products to 150°C.

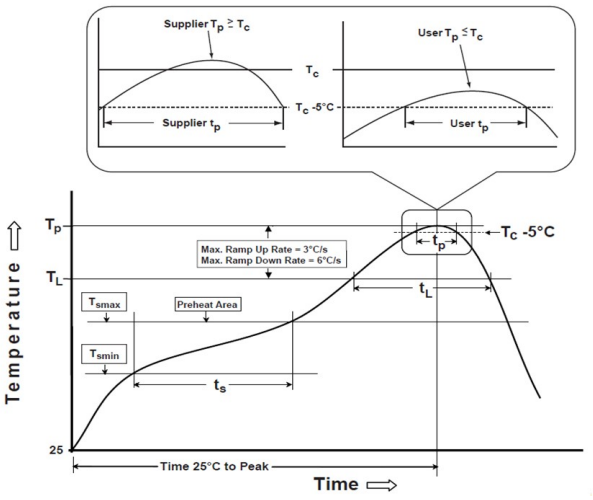
(b) 350°C tip temperature (Max.)

(c) Never contact the ceramic with the iron tip

(d) 1.0mm tip diameter (Max.)

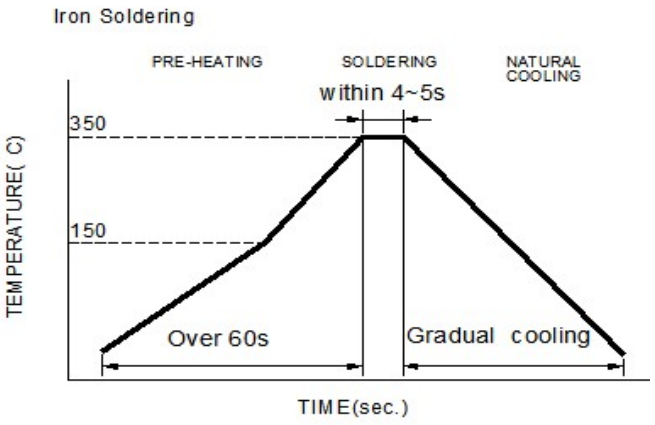
(e) Use a 20 watt soldering iron with tip diameter of 1.0mm

(f) Limit soldering time to 4~5 sec.



Reflow times: 3 times Max

Figure 1: IR Soldering Reflow



Iron Soldering times：1 times max

Figure 2: Iron soldering temperature profiles

NOTE: Specifications subject to change without notice. Please check our website for latest information.

Table (1.1) Reflow Profiles

Profile Type:	Pb-Free Assembly
Preheat -Temperature Min (T_{smin}) -Temperature Max (T_{smax}) -Time (t_s) from (T_{smin} to T_{smax})	 150°C 200°C 60-120seconds
Ramp-up rate ($T_L$to T_p)	3°C /second max.
Liquids temperature (T_L) Time (t_L) maintained above T_L	217°C 60-150 seconds
Classification temperature (T_c)	See Table (1.2)
Time (t_p) at Tc- 5°C (Tp should be equal to or less than Tc.)	< 30 seconds
Ramp-down rate (T_p to T_L)	6°C /second max.
Time 25°C to peak temperature	8 minutes max.

Tp: maximum peak package body temperature, **Tc**: the classification temperature.

For user (customer) **Tp** should be equal to or less than **Tc.**

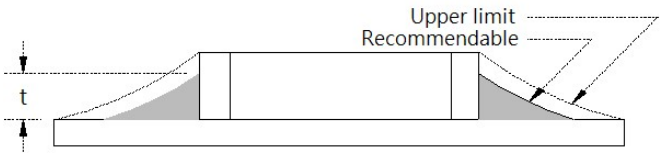
Table (1.2) Package Thickness/Volume and Classification Temperature (T_c)

	Package Thickness	Volume mm^3 <350	Volume mm^3 350-2000	Volume mm^3 >2000
PB-Free Assembly	<1.6mm	260°C	260°C	260°C
	1.6-2.5mm	260°C	250°C	245°C
	≥2.5mm	250°C	245°C	245°C

Reflow is referred to standard IPC/JEDEC J-STD-020F.

7-3. Soldering Volume

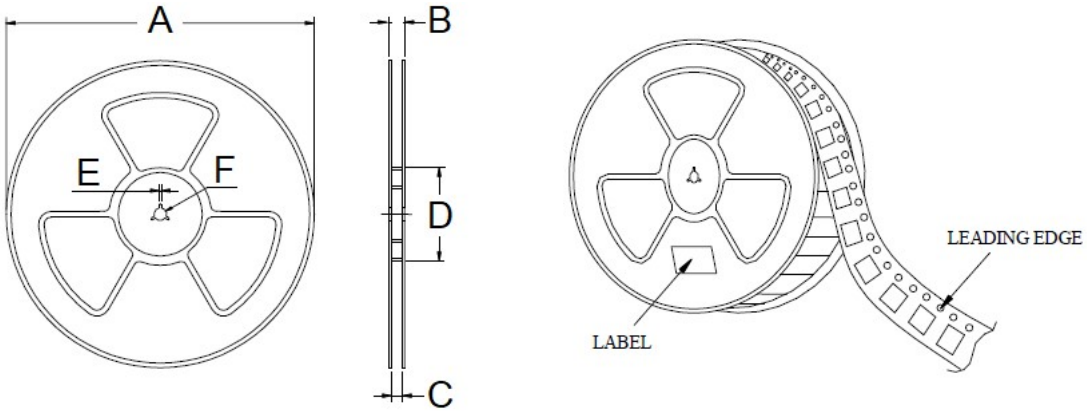
Accordingly increasing the solder volume, the mechanical stress to product is also increased. Exceeding solder volume may cause the failure of mechanical or electrical performance. Solder shall be used not to be exceeded as shown in the Figure below. Minimum fillet height = soldering thickness + 25% product height.



NOTE: Specifications subject to change without notice. Please check our website for latest information.

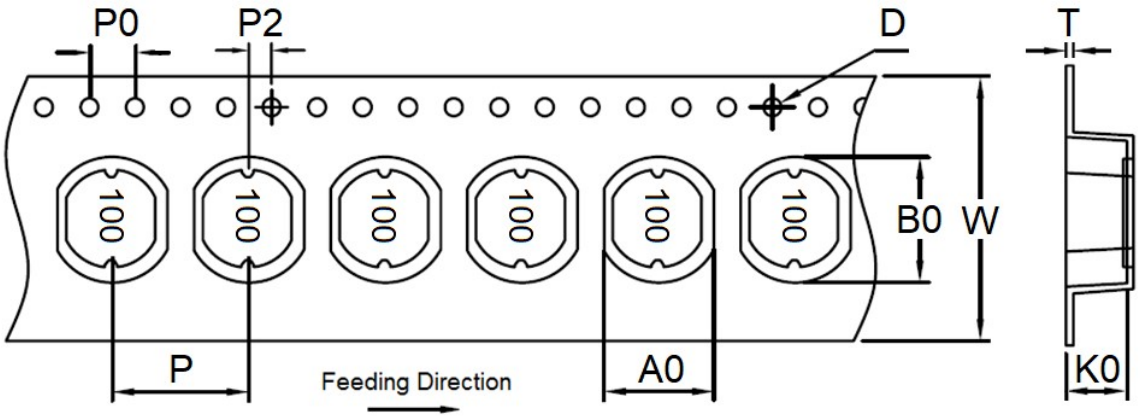
8. Packaging Information

8-1. Reel Dimension (Unit: mm)



Type	A	B	C	D	E	F
13”x24mm	330.00 Ref	30.40 Ref	24.40 Ref	100.00 Ref	2.30 Ref	R6.75

8-2. Tape Dimension (Unit: mm)

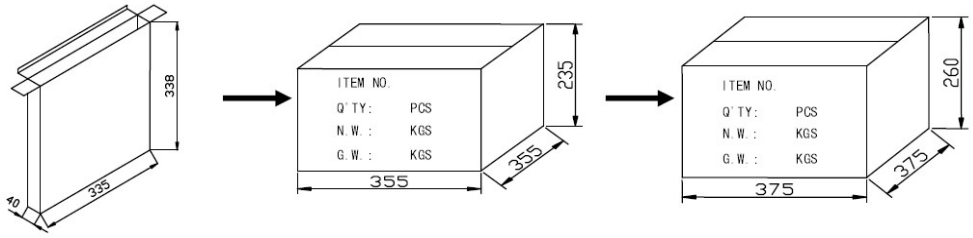


W	A0	B0	K0	P
24.00+0.30/-0.10	9.40±0.10	10.40±0.10	4.30±0.10	12.00±0.10
D	P0	P2	T	-
1.50+0.10/-0.00	4.00±0.10	2.00±0.10	0.35 Ref	-

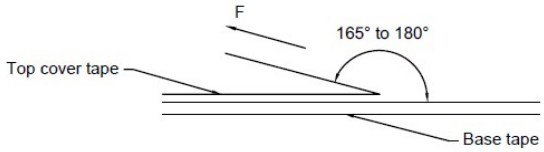
NOTE: Specifications subject to change without notice. Please check our website for latest information.

8-3. Packaging Quantity (Unit: Pcs)

Chip/ Reel	1,000
Inner Box	1,000
Middle Box	5,000
Carton	5,000



8-4. Tearing Off Force



The force for tearing off cover tape is according to the following table, in the arrow direction under the following conditions.

(Referenced ANSI/EIA-481-D-2008 of 4.11 standard)

Room Temp. (°C)	Room Humidity (%)	Room atm (hPa)	Tearing Speed (mm/min)
5~35	45~85	860~1060	300±10

Tape Size	8 mm	12 to 56 mm	72 mm or Wider
Tearing Off Force (grams)	10~100	10~130	10~150

NOTE: Specifications subject to change without notice. Please check our website for latest information.

Application Notice

1. Storage Conditions

To maintain the solderability of terminal electrodes:

(a) Products meet IPC/JEDEC J-STD-020F standard-MSL, level 1.

(b) Recommended products should be used within 6 months from the time of delivery.

(c) The packaging material should be kept where no chlorine or sulfur exists in the air.

2. Transportation

(a) Products should be handled with care to avoid damage or contamination from perspiration and skin oils.

(b) Vacuum pick up is strongly recommended for individual components.

(c) Bulk handling should ensure that abrasion and mechanical shock are minimized.